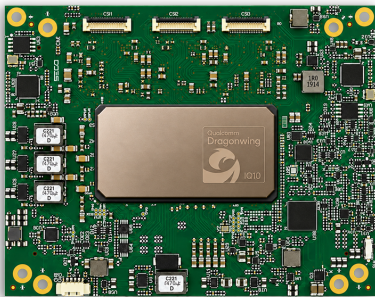




SOM-COM-HPC-A-Dragonwing-IQ10

COM-HPC® 1.3 Client Size A module based on Qualcomm Dragonwing™ IQ10 Series, with up to 700 TOPS of AI Acceleration.

Advanced edge AI acceleration with up to 700 TOPS, enabling robotics, autonomous systems and foundation models in a compact COM-HPC® Client Size A module.



HIGHLIGHTS



CPU

Dragonwing™ IQ10 Series: IQ-I0800MD-AA and IQ-I0800MD-AD



NPU

Up to 700 TOPS of AI Acceleration



CONNECTIVITY

2x 2.5/10GbE; 4x USB 2.0; 4x additional USB ports; 16x PCIe lanes



GRAPHICS

3x DisplayPort (DDI); 1x eDP; 5x CSI camera inputs

COM+HPC®



Powered by



MAIN FIELDS OF APPLICATION



Industrial
Automation



Medical
Robotics



Safety &
Surveillance



Aerospace &
Defence



Robotics

FEATURES

Processor	Dragonwing™ IQ10 Series: IQ-I0800MD-AA (64 GB memory) or IQ-I0800MD-AD (32 GB memory)	USB	4x USB 2.0; Up to 4x USB SS
Memory	Integrated LPDDR5x ECC memory: 64 GB (IQ-I0800MD-AA) or 32 GB (IQ-I0800MD-AD)	PCI-e	1x 8 Lanes PCIe Gen5 1x 4 Lanes PCIe Gen5 1x 2 Lanes PCIe Gen5 4x 1 Lane PCIe Gen3
NPU	Up to 700 TOPS of AI Acceleration	Audio	I2S audio interface
Graphics	Qualcomm® Adreno™ GPU	Serial Ports	2x UART; 2x SPI; 1x general-purpose SPI
Video Interfaces	3x DDI (DisplayPort); 1x eDP.	Other Interfaces	12x SoC GPIOs; 2x I2C; watchdog; fan and management signals; ACPI signals; RTC; interfaces from internal SIL processor via bottom-side on-board connector
Video Processing	4K @ 480 decode; 4K @ 240 encode.	Security	TPM 2.0
Camera	2x CSI2 4-lanes camera inputs via COM-HPC® connector; 3x CSI2 4-lanes camera inputs via bottom-side on-board connectors	Functional Safety Features	Functional safety (FuSa) signals; interfaces from internal SIL processor on bottom-side connector
Mass Storage	UFS 4.0, 2 lanes, up to 512 GB; OSPI flash	CAN Bus	Up to 2x CAN FD interfaces
Networking	2x NBASE-T Ethernet ports, each supporting 2.5GbE / 10GbE		

SOM-COM-HPC-A-Dragonwing-IQ10

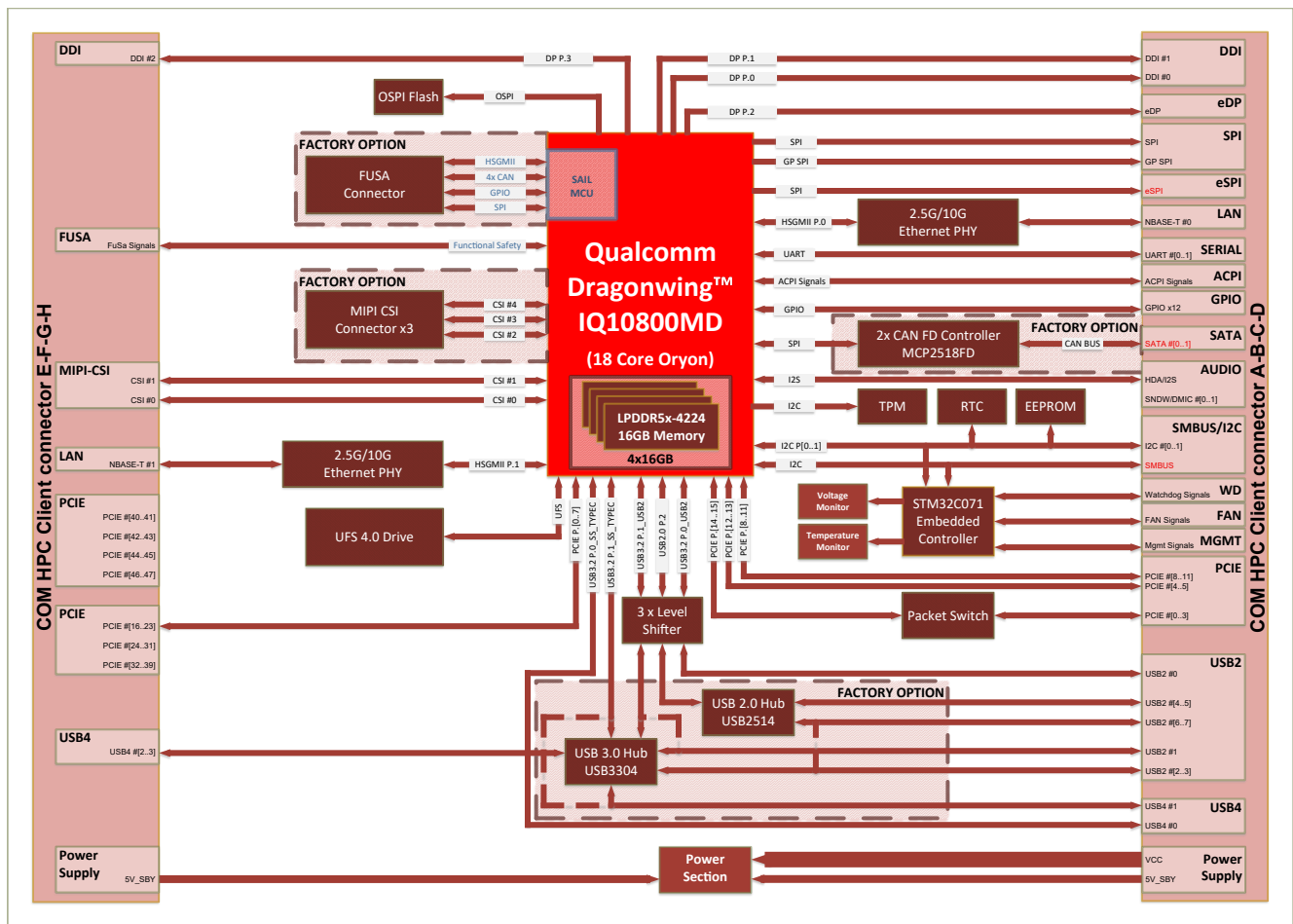
COM-HPC® 1.3 Client Size A module based on Qualcomm Dragonwing™ IQ10 Series, with up to 700 TOPS of AI Acceleration.

FEATURES

Operating System	Clea OS Microsoft Windows 11	Operating Temperature *	0°C to +60°C (commercial); -40°C to +85°C (industrial)
Norms & Standards	CE and FCC compliance specified for ITE target markets	Dimensions	120 x 95 mm (COM-HPC® Client Size A)

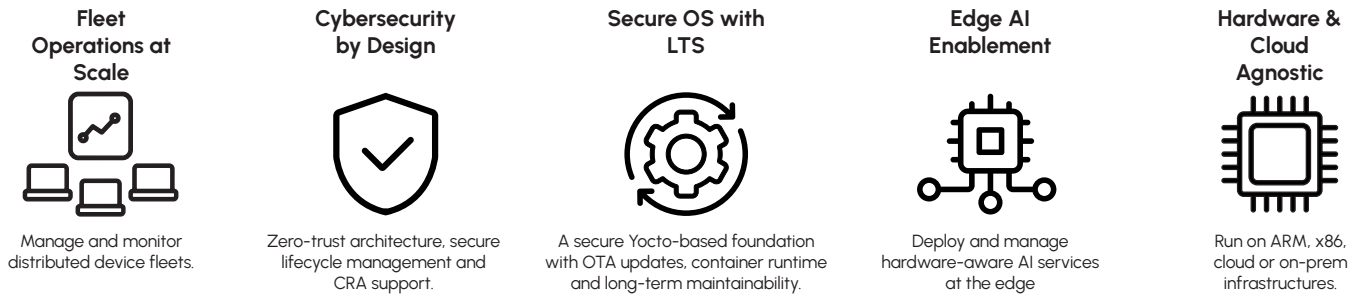
*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.

BLOCK DIAGRAM



Build, Deploy and Maintain Secure Edge Products at Scale.

The secure framework for industrial edge devices, combining fleet operations, cybersecurity, data orchestration and Edge AI enablement.



From Development to Operations

Clea supports the entire product lifecycle, from embedded software development and deployment to fleet operations, maintenance and continuous updates.

